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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10042317	01/11/2002	418	524	3	1714 KEECHAN

**APPLICANTS: Kojima Tosifumi; Takeuchi Hiroki; Obayashi Kazushige;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

JAPAN P.2001-044795 02/21/2001

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiner's initials			ATTORNEY DOCKET NO Q68073
TITLE : Embedding resin, wiring substrate using same and process for producing wiring substrate using same			

U.S. DEPT. OF COMM./PAT & TM-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING		
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.	Print Fig.
TERMINAL DISCLAIMER		Primary Examiner	Application Examiner	
		PREPARED FOR ISSUE		
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.		

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